

Smart I/O iCAN Header – XCL-BSSA



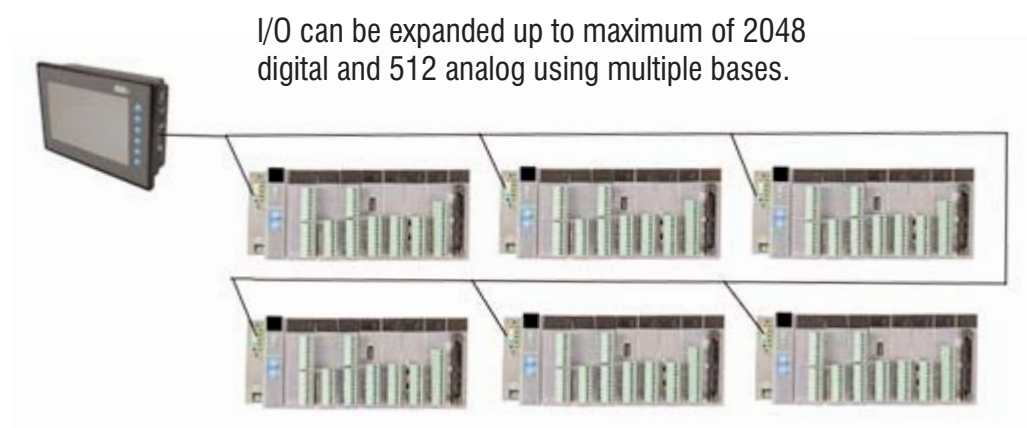
Smart I/O is a real-time, modular I/O system – expanding the application of the i³ family of all-in-one controllers. The Smart I/O iCAN adapter utilizes iCAN communications for the I/O connection with the i³ Controller. The highly efficient and highly reliable nature of iCAN allows a significant amount of I/O to be added while maintaining fast I/O updates.

Modular

Smart I/O is a modular IO system which can add up to 8 I/O modules per base with a wide variety of digital and analog I/O to choose from. Digital I/O includes DC inputs, DC outputs, and Relay outputs. Analog I/O includes 0(4)-20mA/0-10V inputs and outputs, Thermocouple Inputs and RTD Inputs. Modules are available with inputs only, inputs and outputs, and outputs only.

Compact

Smart I/O is very compact, with a flexible footprint that only grows as you add modules. The Smart I/O Base is 3.5”H x 2.375”W – with a depth of only 1.75”. Each I/O module adds only about ¾” of width. Using 16 point modules, the Smart I/O can support 128 I/O points in a footprint of less than 3.5”H x 8.75”W.



Highly Expandable

With digital I/O densities ranging from 8 points to 32 points per module, and an analog density of 4 channels per module – Smart I/O can support as many as 256 digital I/O points and 32 analog I/O points per base. Adding multiple bases to a single i³ control system is very easy. This can allow the number of I/O to grow to literally the limits of the i³ I/O memory space (Digital-2048, Analog-512). Multiple bases can also be used to distribute the I/O to locations closer to the sensors and actuators, saving wiring costs.

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Easy to Setup and Configure

Unlike many I/O systems that are complex and difficult to use, Smart I/O is simply configured using i³ Configurator programming software. Smart I/O bases utilize i³ Configurator Hardware Configuration menu and a “plug and play” approach.

Wiring

The Smart I/O Base should be powered independently from the power supplied to the Smart I/O modules themselves. This offers optimum noise immunity, and helps maintain galvanic isolation between the CAN Network and I/O Power. The recommended approach is to power the CAN network from one power supply, and I/O devices from at least one separate power supply. The Smart I/O bases are powered from the CAN Network.

The Smart I/O base provides two locations to land power wiring – a 5-pin removable network connector, and a 3-pin fixed power connector. While either can be used to power the base, it is recommended to use only the 5-pin removable connector. Leave the 3-pin fixed connector disconnected.

At each end of the network, a 121 ohm, ¼ watt, 1% resistor should be used for termination – installed between the CAN_H and CAN_L terminals. Only appropriate Thin (for <100m) or Thick (<500m) cabling should be used (assuming 125 Kbaud).

General Specification	
Required Power (Steady State)	400mA @24 VDC, max CLASS 2 POWER SUPPLY ONLY
Primary Power Range	11-28 VDC
Output Power	1500mA @ 5 VDC
Terminal Type	M3 Screw Type, Removable
Terminal Torque Range	0.6 Nm (5.2 in-lb)
Accepted Wire Size	14-26AWG (copper)
Wire Stripping Length	7mm
Relative Humidity	5 to 95% Non-condensing
Operating Temp.	-5°C to +50°C
Storage Temp.	-40°C to +75°C
Dimensions (Hx Wx D)	90 x 45 x 60mm [3.54 x 1.77 x 2.36 in]
Weight	114g (4oz)
Vibration & Shock	Per IEC1131-2
Noise Immunity	Per IEC1131-2, IEC61000-4-2, IEC61000-4-3, IEC61000-4-4
CE	Yes
UL & cUL	Class I, Div 2 Groups A, B, C & D

Part Numbers**	Description
XCL - BSSA	Smart I/O iCAN Adapter
XBE-DC16B	Expansion Module 16 Point, (9-30)VDC Input
XBE-DC32A	Expansion Module 32 Point, 24VDC
XBE-DR16A	Expansion Module 8 Point 24VDC Input, 8 Point Relay Output
XBE-RY16A	Expansion Module 16 Point Relay Output
XBE-TP16A	Expansion Module 16 Point Transistor Output (Source)
XBE-TP32A	Expansion Module 32 Point Transistor Output (Source)
XBF-AD04A	Expansion Module 4 Analog Input
XBF-AH04A	Expansion Module 2 Analog Input , 2 Analog Output
XBF-RD04A	Expansion Module 4 PT100 Inputs

** Please ask IMO for more information about expansion modules.

Communications Specifications	
Data Transmission	iCAN
Flow Control	CAN bitwise arbitration
Connector	M3 Screw Type, 5-pin Removable Terminal Block
Architecture	Daisy-chain or Trunkline-Dropline
Node ID config.	Digital Rotary Switches (2)
Legal Node Ids	1 to 79 decimal
Inactivity Timeout	Configurable from Software
i ³ Config. Version	9.4 or later
i ³ Firmware Version	12.98 or later

I/O Specifications	
Compatible I/O	XGB I/O
Bases Supported (per system)	16
Modules Supported (per base)	8
Digital I/O, max (per base)	256 (Inputs + Outputs)
Analog I/O, max (per base)	32 (Inputs + Outputs)
I/O Limitations (per system)	2048 Digital In, 2048 Digital Out, 512 Analog In, 512 Analog Out
Power Supplied for I/O modules	1500mA @ 5V DC maximum